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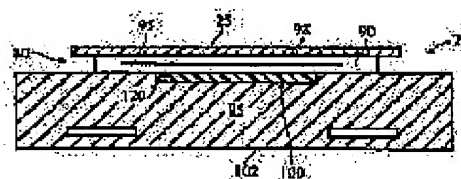
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(54) ELECTROSTATIC CHUCK HAVING REGULAR PAD FOR TRANSMITTING HEAT

(57)Abstract:

PROBLEM TO BE SOLVED: To attain a substantially uniform stabilized temperature profile from the central part over the peripheral part by setting the thermal resistance of a pad interposed between a conductive member receiving surface and the lower surface of a base sufficiently higher or lower than that of the base.

SOLUTION: The electrostatic chuck comprises an electrostatic member 80 supported on a base 85 in a process chamber 20. The electrostatic member 80 comprises a dielectric, i.e., an insulator 90, covering at least one electrode 95. A regular pad 100 for transmitting heat is interposed between the receiving surface 98 of the electrostatic member 80 and the lower surface of the base 85 and regulates transmission or flow of heat from a substrate 25. Preferably, the regular pad 100 for transmitting heat is interposed between the electrostatic member 80 and the base 85 and regulates transmission or flow of heat from a substrate 25 through the electrostatic member 80 and the base 85. A sufficiently high difference of thermal resistance is selected between the pad 100 and the base 85.



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